

SECURITY CODE		MITSUBISHI ELECTRIC CORPORATION					
SPEC.NAME Customer's Std. Spec.	Prepared by	S.Iura	R E V	A	S.Iura	B	S.Iura
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HIGH VOLTAGE IGBT MODULE TARGET SPECIFICATION

- Type number **CM1800HC-34N**
(1.7kV / 1.8kA single-HVIGBT with CSTBT)
- Structure Flat base type (Insulated package, AlSiC base plate)
- Application & Customer High power converters and inverters
- Outline 130 × 140 × 38 (L. W. H)
- Related specifications
- Maximum ratings

Item	Symbol	Conditions	Ratings	Unit
6.1 Collector-emitter voltage	V_{CES}	$V_{GE}=0V, T_j=25^\circ C$	1700	V
6.2 Gate-emitter voltage	V_{GES}	$V_{CE}=0V, T_j=25^\circ C$	±20	V
6.3 Collector current	I_C	$T_C=80^\circ C$	1800	A
	I_{CM}	Pulse (note1)	3600	A
6.4 Emitter current	I_E (note2)		1800	A
	I_{EM} (note2)	Pulse (note1)	3600	A
6.5 Maximum collector dissipation	P_C (note3)	$T_C=25^\circ C$, IGBT part	9600	W
6.6 Isolation voltage	V_{iso}	Charged part to base plate, rms sinusoidal, AC60Hz 1min.	4000	V
6.7 Junction temperature	T_j	—	-40 ~ +150	°C
6.8 Storage temperature	T_{stg}	—	-40 ~ +125	°C
6.9 Operating temperature	T_{op}	—	-40 ~ +125	°C
6.10 Maximum turn-off switching current	—	$T_j=125^\circ C, V_{CC}\leq 1200V$ $V_{GE}=\pm 15V, V_{CE}\leq 1700V$	1800	A
	—	$T_j=125^\circ C, V_{CC}\leq 1200V$ $V_{GE}=\pm 15V, V_{CE}\leq 1200V$	3600	A
6.11 Short-circuit capability (maximum pulse width)	—	$T_j=125^\circ C, V_{CC}\leq 1200V$ $V_{GE}=\pm 15V, V_{CE}\leq 1700V$ [See Fig.1(b)]	10	μs
6.12 Maximum reverse recovery instantaneous power (note2)	—	$T_j=125^\circ C, V_{CC}\leq 1200V$ $V_{EC}\leq 1700V$	750	kW

Note 1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jmax} rating (125°C)

Note 2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

Note 3. Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

HIGH VOLTAGE IGBT MODULE SPECIFICATION	HCM-1280-B	(HV-SETSU)	PAGE 1 / 4
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7. Electrical characteristics

Item	Symbol	Conditions	Limits			Unit	
			Min.	Typ.	Max.		
7.1 Collector cutoff current	I_{CES}	$V_{CE}=V_{CES}$ $V_{GE}=0V$	$T_j=25^{\circ}C$	—	—	6	mA
			$T_j=125^{\circ}C$	—	—	12	
7.2 Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=180mA, V_{CE}=10V, T_j=25^{\circ}C$	—	7.0	—	V	
7.3 Gate leakage current	I_{GES}	$V_{GE}=V_{GES}, V_{CE}=0V, T_j=25^{\circ}C$	—	—	0.5	μA	
7.4 Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=1800A$ $V_{GE}=15V$ (note4)	$T_j=25^{\circ}C$	—	2.15	—	V
			$T_j=125^{\circ}C$	—	2.40	—	
7.5 Input capacitance	C_{ies}	$V_{CE}=10V$ $V_{GE}=0V$ $T_j=25^{\circ}C$	$f=100kHz$	—	264	—	nF
7.6 Output capacitance	C_{oes}		$f=100kHz$	—	14.4	—	nF
7.7 Reverse transfer capacitance	C_{res}		$f=100kHz$	—	4.2	—	
7.8 Total gate charge	Q_G	$V_{CC}=850V, I_C=1800A, T_j=25^{\circ}C$ $V_{GE}=0V \rightarrow 15V$	—	10.2	—	μC	
7.9 Emitter-collector voltage (FWDi forward voltage)	V_{EC} (note3)	$I_E=1800A$ $V_{GE}=0V$ (note4)	$T_j=25^{\circ}C$	—	2.40	—	V
			$T_j=125^{\circ}C$	—	2.10	—	
7.10 Turn-on delay time	$t_{d(on)}$	Half bridge switching operation [See Fig.1(a), Fig.2, Fig.3] $V_{CC}=850V, T_j=125^{\circ}C$	—	1.00	—	μs	
7.11 Turn-on rise time	t_r		—	0.35	—		
7.12 Turn-off delay time	$t_{d(off)}$		—	2.00	—		
7.13 Turn-off fall time	t_f		—	0.25	—		
7.14 Reverse recovery time	t_{rr} (note3)		—	1.00	—		
7.15 Reverse recovery charge	Q_{rr} (note3)	IGBT(N): IGBT operation $I_C=1800A, V_{GE1}=-V_{GE2}=15V,$ $R_{G(on)}=0.9\Omega, R_{G(off)}=2.2\Omega$	—	540	—	μC	
7.16 Turn-on switching energy	E_{on}	IGBT(P): FWDi operation $I_E=1800A, V_{GE3}=-15V,$ $R_{G(on)}=0.9\Omega, R_{G(off)}=2.2\Omega$	—	600	—	mJ/P	
7.17 Turn-off switching energy	E_{off}		—	540	—		
7.18 Reverse recovery energy (FWDi switching energy)	E_{rec} (note3)		—	360	—		

A
A
A
A
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A
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A
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A
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A
A
B

Note 4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

8. Thermal characteristics

Item	Symbol	Conditions	Limits			Unit
			Min.	Typ.	Max.	
8.1 Thermal resistance	$R_{th(j-c)Q}$	Junction to case, IGBT part	—	—	13.0	K/kW
8.2 Thermal resistance	$R_{th(j-c)R}$	Junction to case, FWDi part	—	—	28.0	
8.3 Contact thermal resistance	$R_{th(c-f)}$	Case to fin, conductive grease applied (note5)	—	11.0	—	

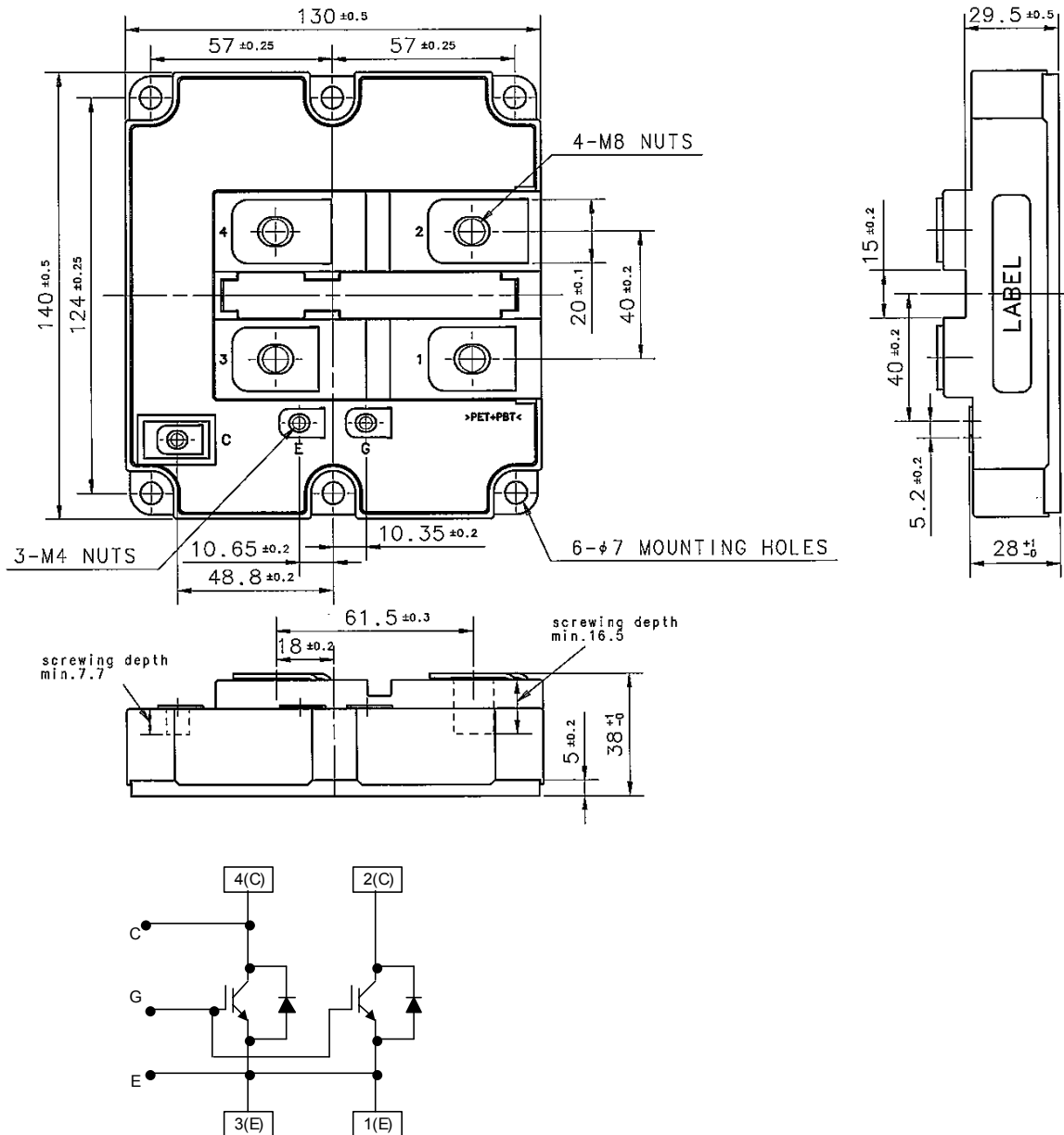
Note 5. Thermal conductivity is 1W/mK with a thickness of 100 μm .

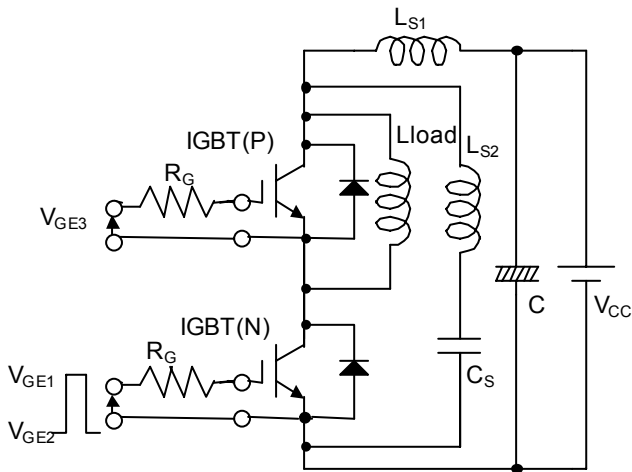
9. Mechanical characteristics

Item	Symbol	Conditions	Limits			Unit
			Min.	Typ.	Max.	
9.1 Mounting torque	—	Main terminal screw : M8	7.0	—	13.0	N·m
9.2 Mounting torque	—	Mounting screw : M6	3.0	—	6.0	
9.3 Mounting torque	—	Auxiliary terminal screw : M4	1.0	—	2.0	
9.4 Mass	—	—	—	0.8	—	kg
9.5 CTI	—	—	600	—	—	—
9.6 Clearance	—	—	19.5	—	—	mm
9.7 Creepage distance	—	—	32.0	—	—	mm

A

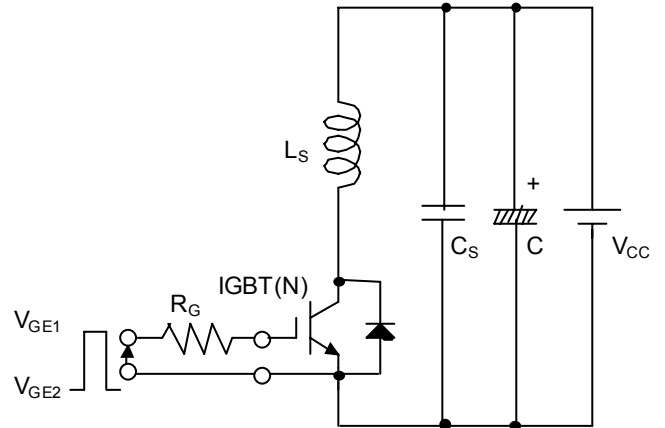
10. Outline drawing & Circuit diagram B





C=2[mF],Cs=20[μF],LS1=500[nH],LS2=150[nH]

Fig. 1 (a) – Switching test circuit



C=2[mF],Cs=40[μF],LS=80[nH]

Fig. 1 (b) – Short circuit test circuit

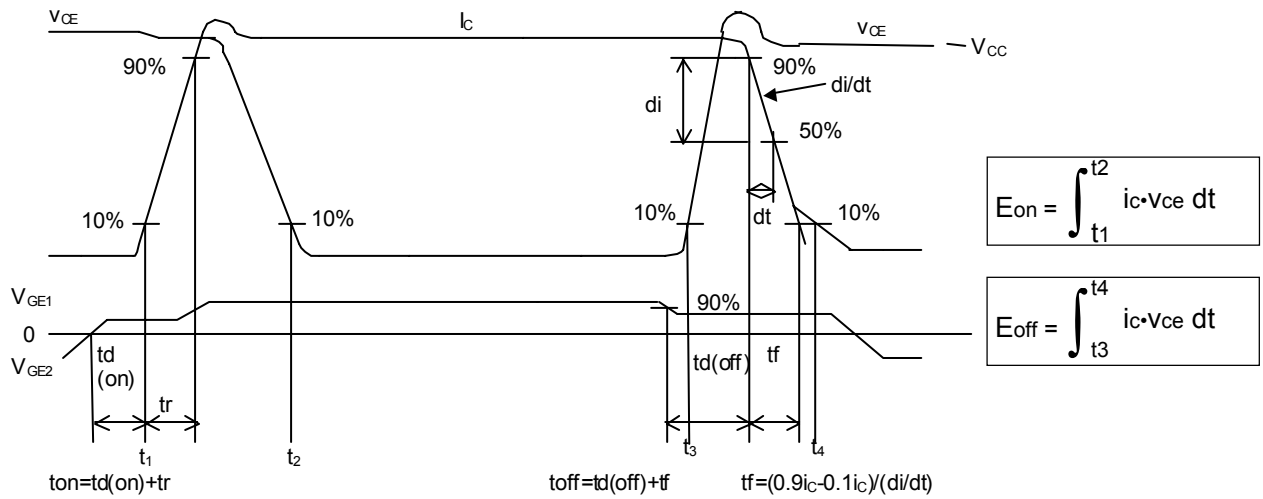


Fig. 2 - Definitions of switching time & energy of IGBT part

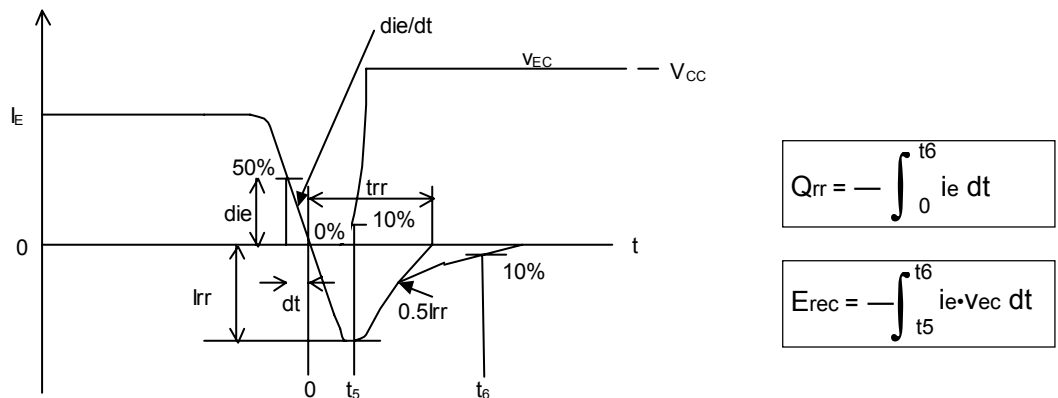


Fig. 3 - Definitions of switching time, charge & energy of FWDi part